Contribution ID: **65**   Type: **not specified**

A3D3: Community Engagement, Education, Outreach

Thursday 27 October 2022 10:10 (1 hour)

A3D3 aims to be a nexus for exchanging new ideas, algorithms and tools between scientific domains, AI communities and industry partners for AI-Hardware co-design. In this presentation, we will show efforts based on strong foundation on the Fast Machine Learning (FastML) community efforts. Our on-going programs on Postbaccalaurate Fellowships, Training, Education, and strong connection with industry leaders in AI hardware, HPCs, and cloud computing via integration with the FastML community and university research partnerships.

Research

Education and Outreach

Data & Cyberinfrastructure

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Session Classification: Poster session I